

# SOT619-3

plastic, heatsink very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.9 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN48
<b>Package type industry code</b>	HVQFN48
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	7-9-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.85	-	7	7.15	mm
E	package width	6.85	-	7	7.15	mm
A	seated height	[tbd]	-	0.9	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.9	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	

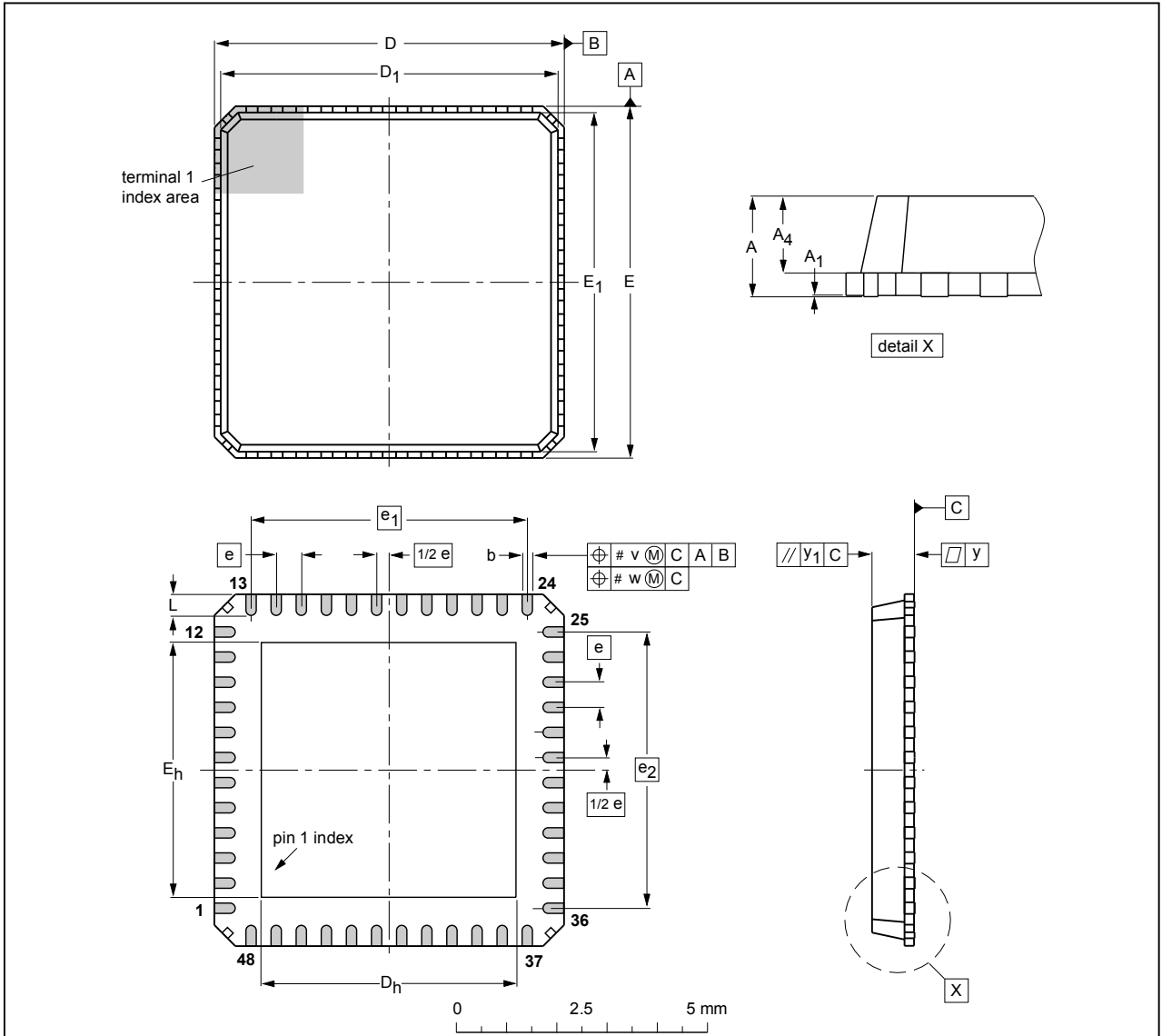


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## 2. Package outline

HVQFN48: plastic, heatsink very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>4</sub>	b	D	D <sub>1</sub>	D <sub>h</sub>	E	E <sub>1</sub>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1.00	0.05 0	0.80 0.65	0.30 0.18	7.15 6.85	6.85 6.65	5.25 4.95	7.15 6.85	6.85 6.65	5.25 4.95	0.5	5.5	5.5	0.50 0.30	0.2	0.1	0.08	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT619-3		MO-220			-01-08-31 01-09-07

Fig. 1. Package outline HVQFN48 (SOT619-3)

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### 3. Legal information

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Date of release: 8 February 2016

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